IPC ASSOCIATION ELECTRONIC		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information			
Supplier	r Information				•										
Company name* Company un				nique ID			Unique ID Authority					Response Date*			
nsemi												2025-06-08			
Contact N	ame	Title - Contact			F	Phone - Contact*					Email - Contact*				
Product-I	Env-Stewards	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com					
uthorize	d Representative*	Title - Representative			F	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	ective Date		ing Site	V	Veight*	UOM	Unit Type	
		MC14081BDG LOG CMOS GATE		E AND QUAD		2025-06-08	PH1			1	22.04	mg	Each		
<b>I</b> anufa	cturing Proccess Inform	ation													
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD		-STD-020 MSL	Rating	Peak Process Body Temper		Temperatur	ture Max Time at Peak Tempe		Temperatu	ire Numb	er of Reflow Cyc	eles
Matte Tin (Sn) - annealed CU			U Alloy 1			260		C 30		30 secon		onds 3			
omments															
vel 1 - m	aximum time at peak tempera	ture during so	ldering is 10-3	30 seconds											
or more	information regarding materia	al composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correction this form. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier near not or the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall appl											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg
Die Attach	4.44	mg		Epoxy resin	proprietary data		0.111	mg
			Supplier	Silver (Ag)	7440-22-4		3.552	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.2886	mg
			Supplier	Acrylic resins	Proprietary Data		0.4884	mg
Lead Frame	69.62	mg	Supplier	Silver (Ag)	7440-22-4		0.7658	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1392	mg
			Supplier	Iron (Fe)	7439-89-6		1.8101	mg
			Supplier	Copper (Cu)	7440-50-8		66.9048	mg
Mold Compound-Black	43.43	mg		Epoxy resin	proprietary data		5.7762	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0869	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		37.567	mg
Plating	3.27	mg	Supplier	Tin (Sn)	7440-31-5		3.27	mg
Wire Bond - Cu	0.3	mg	Supplier	Palladium (Pd)	7440-05-3		0.0048	mg
			Supplier	Copper (Cu)	7440-50-8		0.2952	mg